



#### **DUAL N-CHANNEL ENHANCEMENT MODE MOSFET**

### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C
001/	30mΩ @ V <sub>GS</sub> = 10V	6.2A
30V	42mΩ @ V <sub>GS</sub> = 4.5V	5.2A

## **Description and Applications**

This MOSFET is designed to minimize the on-state resistance ( $R_{DS(ON)}$ ) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Body Control Electronics
- Power Management Functions
- DC-DC Converters

### **Features and Benefits**

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at

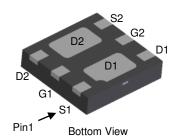
https://www.diodes.com/products/automotive/automotive-products/.

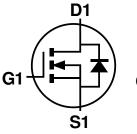
- This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.
  - https://www.diodes.com/quality/product-definitions/
- An Automotive-Compliant Part is Available Under Separate Datasheet (<u>DMN3032LFDBQ</u>)

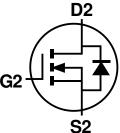
### **Mechanical Data**

- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu Annealed over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208
- Terminals Connections: See Diagram Below
- Weight: 0.0065 grams (Approximate)

U-DFN2020-6 (Type B)







Internal Schematic

### **Ordering Information** (Note 4)

Part Number	Case	Packaging
DMN3032LFDB-7	U-DFN2020-6 (Type B)	3,000/Tape & Reel
DMN3032LFDB-13	U-DFN2020-6 (Type B)	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



# **Marking Information**

Site 1

U-DFN2020-6 (Type B)



N5 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: H = 2020) M = Month (ex: 9 = September)

Date Code Kev

Date Code Key												
Year	2012		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	Z		Н		J	K	L	М	N	0	Р	R
Month	Month Jan Feb Mar Apr May Jun Jul Aug Sep Oct Nov Dec											
MOHIII	Jan	reb	IVIAI	Apr	iviay	Jun	Jul	Aug	Sep	OCI	INOV	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

Site 2



N5 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 0 = 2020) W = Week (ex: a = Week 27; z Represents Week 52 and 53)

X = Internal Code (ex: U = Monday)

Date Code Key

Year	2012	 2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	2	 0	1	2	3	4	5	6	7	8	9

Week	1-26	27-52	53
Code	A-Z	a-z	Z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	Т	U	V	W	X	Υ	Z



# Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			$V_{DSS}$	30	V
Gate-Source Voltage			Vgss	±20	V
Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V Steady T <sub>A</sub> = +25°C State T <sub>A</sub> = +75°C		I <sub>D</sub>	6.2 5.0	А	
Maximum Continuous Body Diode Forward Currer	nt (Note 6)		Is	2	Α
Pulsed Body Diode Forward Current (370µs Pulse	, Duty Cycl	e = 1%)	I <sub>SM</sub>	20	Α
Pulsed Drain Current (10μs Pulse, Duty Cycle = 1	%)		Ірм	25	Α
Avalanche Current (Note 7) L = 0.1mH			las	12	Α
Avalanche Energy (Note 7) L = 0.1mH			E <sub>AS</sub>	10	mJ

# **Thermal Characteristics**

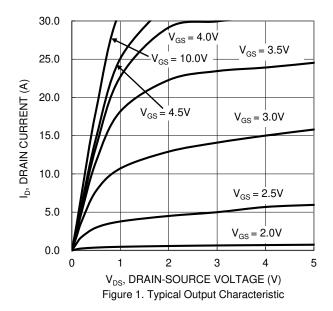
Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)		PD	1.0	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	р	127	°C/W
Thermal nesistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	75	C/VV
Total Power Dissipation (Note 6)		PD	1.7	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	р	72	
Thermal nesistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	43	°C/W
Thermal Resistance, Junction to Case (Note 6)		RθJC	9	
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

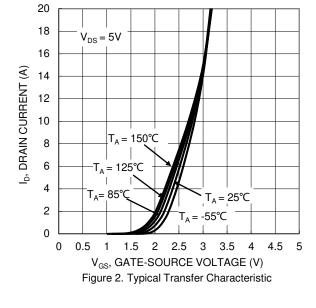
# **Electrical Characteristics** (@TA = +25°C, unless otherwise specified.)

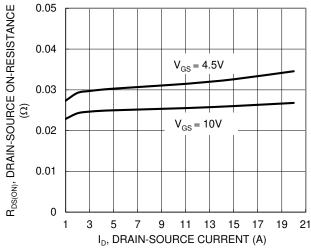
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BVDSS	30	_	_	V	$V_{GS} = 0V, I_{D} = 250\mu A$
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	IDSS	_	_	1.0	μA	$V_{DS} = 30V$ , $V_{GS} = 0V$
Zero Gate Voltage Drain Current T <sub>J</sub> = +150°C (Note 9)	I <sub>DSS</sub>	_		100	μΑ	$V_{DS} = 30V, V_{GS} = 0V$
Gate-Source Leakage	Igss	_		±100	nA	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1.0	1.5	2.0	٧	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$
Static Drain-Source On-Resistance	Dagger	_	25	30	mΩ	$V_{GS} = 10V, I_{D} = 5.8A$
Static Drain-Source On-Nesistance	RDS(ON)	_	30	42	11122	$V_{GS} = 4.5V, I_D = 4.8A$
Diode Forward Voltage	V <sub>SD</sub>	_	0.75	1.2	٧	$V_{GS} = 0V$ , $I_{S} = 1A$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	Ciss	_	500		рF	V 45V V 0V
Output Capacitance	Coss	_	52		pF	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	44		pF	1 = 1.01/1112
Gate Resistance	Rg	_	2.3		Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	5.0	_	nC	
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	10.6	_	nC	V 15V I- 50A
Gate-Source Charge	Qgs	_	1.3	_	nC	$V_{DS} = 15V, I_{D} = 5.8A$
Gate-Drain Charge	$Q_{gd}$	_	1.8	_	nC	
Turn-On Delay Time	td(on)	_	2.2	_	ns	
Turn-On Rise Time	t <sub>R</sub>	_	2.6	_	ns	$V_{DD} = 15V, V_{GS} = 10V,$
Turn-Off Delay Time	tD(OFF)	_	9.7		ns	$R_L = 2.6\Omega$ , $R_G = 3\Omega$
Turn-Off Fall Time	tF	_	2.0		ns	

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
7. I<sub>AS</sub> and E<sub>AS</sub> ratings are based on low frequency and duty cycles to keep T<sub>J</sub> = +25°C.
8. Short duration pulse test used to minimize self-heating effect.
9. Guaranteed by design. Not subject to product testing. Notes:









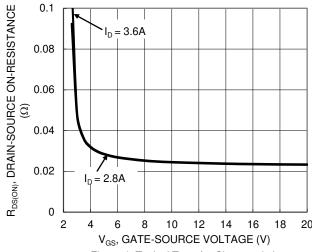
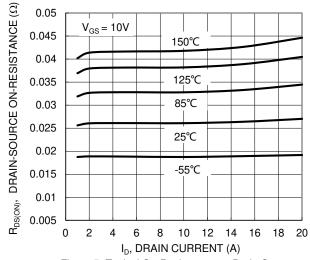


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

Figure 4. Typical Transfer Characteristic



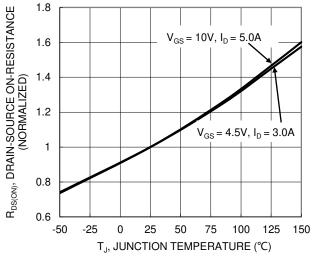


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

Figure 6. On-Resistance Variation with Temperature



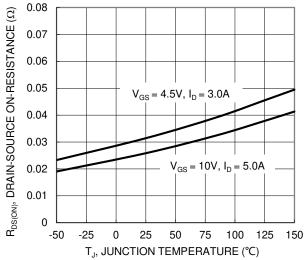
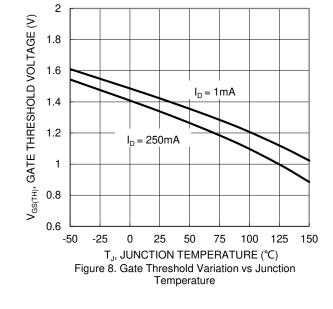


Figure 7. On-Resistance Variation with Temperature



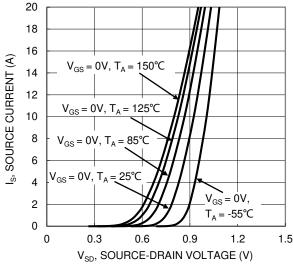
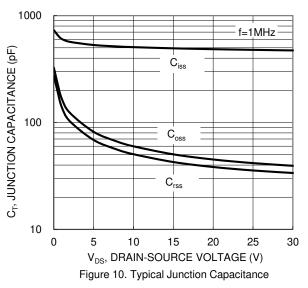
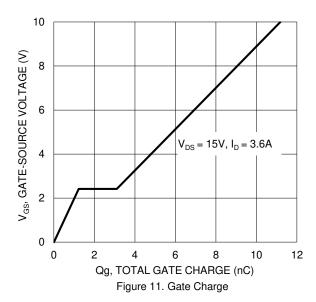
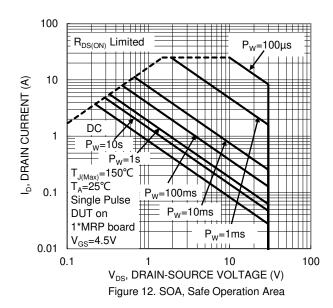


Figure 9. Diode Forward Voltage vs. Current









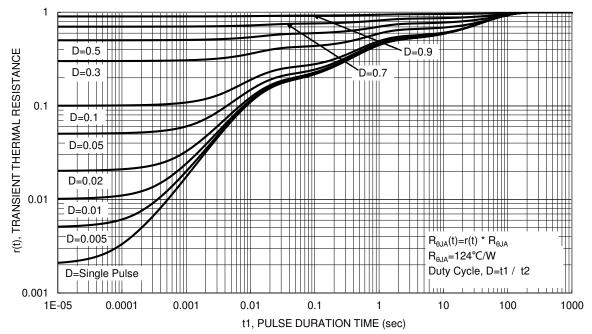
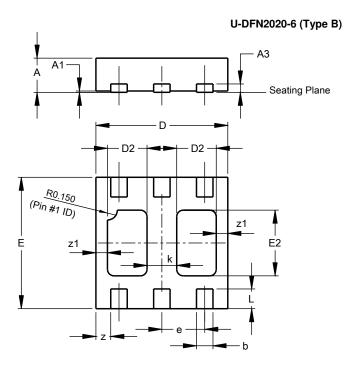


Figure 13. Transient Thermal Resistance



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

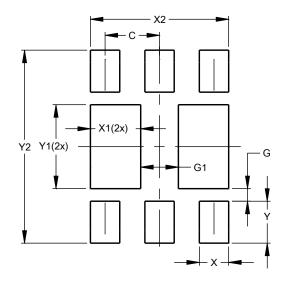


U-DFN2020-6 Type B							
Dim	Min	Max	Тур				
Α	0.545	0.605	0.575				
A1	0.00	0.05	0.02				
A3	-	-	0.13				
b	0.20	0.30	0.25				
D	1.95	2.075	2.00				
D2	0.50	0.70	0.60				
е	1	1	0.65				
Е	1.95	2.075	2.00				
E2	0.90	1.10	1.00				
k	-	-	0.45				
L	0.25	0.35	0.30				
Z	-	-	0.225				
z1	-	-	0.175				
All	Dimens	ions in	mm				

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### U-DFN2020-6 (Type B)



Dimensions	Value (in mm)		
С	0.650		
G	0.150		
G1	0.450		
X	0.350		
X1	0.600		
X2	1.650		
Υ	0.500		
Y1	1.000		
Y2	2.300		



#### **IMPORTANT NOTICE**

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

#### **LIFE SUPPORT**

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
  - 1. are intended to implant into the body, or
  - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2020, Diodes Incorporated

www.diodes.com